

Standard PCB Technical Capacity

Layers and Type		1-30 layers standard PCB, Blind Vias and Buried Vias Board (no cross blind)	
Track Space		5mil /5 mil	
Hole Size(mm)	Board Thickness<2.0mm	0.25mm	
	Board Thickness≥2.0mm	Aspect ratio=10	
Board Thickness	Double Sided		0.4~3.0mm
	Multilayer	4L:0.8mm; 6L:1.0mm; 8L:1.6mm; 10L:2.0mm; Maximum Board Thickness:6.0mm	
Maximum Size		508mm*609mm	
Minimum Size		25.4mm*25.4mm	
The Distance Between the Track to Board Edge		10mil	(20mil for v-cut)
Minimum Space Between the Holes		12mil	
Minimum Space Between Hole to Track (Inner layer)		10mil	
Maximum Layer		30L for prototype, 12L for mass production	
Solder mask	Solder Mask opening		5mil
	Solder Mask Bridge		10mil (IC connect space)
	Color	Green, White, Yellow, Black, Red,Purple etc.	
		Gloss and Matt	
Silkscreen	Tack Width mil		7/5mil
	Color		White, Black, Yellow
		White preferred	
Technique		HAL, Immersion Gold, Immersion Tin, Plated Tin, Immersion Silver, OSP, Flux	
Plating Thickness (u")	Electrical Gold	Nickel Thickness	100-150U"
		Gold Thickness	0.5-3U" (flash gold) 1-3U"(hard gold)
	Immersion gold	Nickel Thickness	100-150U"
		Gold Thickness	1-3U"
PTH plating Thickness		640~980 U" (16um~25um)	
Surface Copper Thickness		0.5~3 oz	
Surface copper plating (u≤8)		640-800 U"	
Characteristic Impedance Control tolerance (Ω)		±10%	
PTH hole tolerance		0.075 mm	
NPTH hole tolerance		0.05 mm	
Outline Minimum tolerance		0.127 mm	
Minimum Tooling Strip		5mm	
		0.2mm for v-cut	

Special PCB Technical Capacity

Layers and Type		1-30 layers standard PCB, Blind Vias and Buried Vias Board			
Minimum Track Space		4mil /4 mil		3mils partial allowed	
Minimum Annular Ring		3 mils for via hole 6mils for component hole			
Minimum Hole Size(mm)		Board Thickness<2.0mm	0.15mm		Finished Hole
		Board Thickness≥2.0mm	Aspect ratio≤8		
Board Thickness	Double Sided		0.2~3.0mm		
	Multilayer	4L:0.6mm; 6L:0.8mm; 8L:1.2mm; 10L:1.6mm; Maximum Board Thickness:6.0mm			
Maximum Size		1000mm*1200mm			
Minimum Size		3mm*3mm			
The Distance Between the Track to Board Edge		10mil		20mil for v-cut	
Minimum Space Between the Holes		12mil			
Minimum Space Between Hole to Track (Inner layer)		10mil			
Maximum Layer		30L for prototype, 12L for mass production			
Solder mask	Solder Mask opening		3mil		
	Solder Mask Bridge		10mil (IC connect space)		
	Color	Green, White, Yellow, Black, Purple etc.		Gloss and Matt	
Silkscreen	Minimum Tack Width mil		6/4mil		
	Color		White, Black, Yellow		White preferred
Technique		HAL, Immersion Gold, Immersion Tin, Plated Tin, Immersion Silver, OSP, Flux			
Plating Thickness (u")	Electrical Gold	Nickel Thickness	Maximum:600 U"	Minimum:100 U"	
		Gold Thickness	Maximum:50 U"	Minimum:0.5 U"	
	Immersion gold	Nickel Thickness	Maximum:600 U"	Minimum:100 U"	
		Gold Thickness	Maximum:5 U"	Minimum:1 U"	
PTH plating Thickness		Maximum:1200 U"		Minimum:640 U"	
Surface Copper Thickness		Maximum:6/6 oz		Minimum:0.5/0.5 oz	
Surface copper plating ($\mu\leq 8$)		Maximum:1200 U"		Minimum:800 U"	
Characteristic Impedance Control tolerance (Ω)		$\pm 10\%$			
PTH hole tolerance		0.075 mm			
NPTH hole tolerance		0.05 mm			
Outline Minimum tolerance		0.1 mm			0.2mm for v-cut
Minimum Tooling Strip		5mm			